

SBC-3.5-RK3568

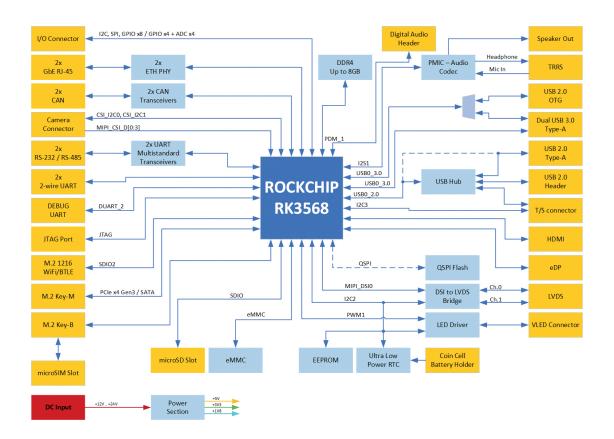
Up to 4K Multimedia Arm® Computing with Wireless and Wired Connectivity

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Mali-C3S 1-Core-2EE GPU OpenGL ES 1.1/2.0/3.2 Vulkan 1.0 and 11 OpenCL 2.0 Full Profile Embedded Video CODEC H265/H.264/VP9 4K@60fps HW decoding VP8/VCI/MPEG-4/MPEG-2/MPEG-1 1080p @60fps HW decoding H265/H.264 1080p@60fps HW encoding H265/H.264 1080p@60fps HW encoding VP8/VCI/MPEG-4/MPEG-2/MPEG-1 1080p @60fps HW decoding H265/H.264 1080p@60fps HW encoding Supports 3 independent video outputs HDMI® LVDS single / dual channel interface eDP 1.3 interface Other Interfaces					
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Video Interfaces HDMI® LVDS single / dual channel interface eDP 1.3 interface HDMI® LVDS single / dual channel interface 2x 2-lanes MIPI-CSI camera connector or 1x 4-lan M.2 Socket 2 Key M for AI accelerator modules Dedicated connector for I2C touch screen controll 8x GPIOs or 4x GPIOs + 4 A _{bc} (factory configuration	Ł				
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Video LVDS: up to 1920 x 1080 @60Hz 2x CAN, 1x 12C, 1x SPI DP: up to 4096 x 2160 (4k) 0 0					
eMMC 5.1 drive soldered on-board, up to 64GB (first boot					
Mass Storage device) microSD slot (second boot device) I2C flash Operating System Linux Yocto Android					
QSPI flash (factory option) 2x Gigabit Ethernet ports, implemented using TI DP83867 Operating Temperature* O°C to +60°C (Commercial version)*					
Ethernet PHY on RGMI interface coming from SoC Optional on-boad M.2 1216 module WLAN 802.11 a/b/g/n/ac + BT 5.0					
M.2 Socket 2 Key B for LTE module + microSIM card slot on-board * Measured at any point of SECO standard heatspreader for this prod during any and all times (including start-up). Actual temperature will w	/idely				
depend on application, enclosure and/or environment. Upon customer consider application-specific cooling solutions for the final system to k heatspreader temperature in the range indicated.					



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BLOCK DIAGRAM





Streamline and expedite your edge computing implementations

EDGEHOG OS

A flexible operating system that adapts to your needs, thanks to the customization tool and Docker support. Reliability and security are built-in through a dual-partition system and native integration with Exein's robust AI-based protection.

DEVICE MANAGER

PORTAL

Update, configure, and manage remote devices. Optimize time and costs to maximize operational efficiency and security without the need for costly field interventions.

DATA ORCHESTRATION

Integrate third-party services, simplify data flows and analysis, and enhance business efficiency by enabling easy and fast utilization of AI. Analyze data from remote devices, customize the user experience with applications tailored to user needs, and manage user rights, company access, and tenant privileges.



